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SyChip Announces World's Thinnest IEEE 802.11g Embedded Module for the Mobile Phone Market

WLAN6102 boast 0.9 mm in height and 88 mm³ in total package volume.

PLANO, Texas (Jan. 5, 2006) - SyChip, the leader in Radio Frequency Chip Scale Modules (CSM) today announced the WLAN6102 as the first commercial product utilizing SyChip's proprietary Integrated Passive Device (IPD) technology. The WLAN6102, SyChip's 3rd generation module technology, enables wireless-LAN connectivity in mobile converged devices where size, cost, and system integration are critical design criteria.

"The smart phone segment of the mobile phone market is growing at a rate of more than 50 percent annually, according to IDC's November 2005 Market Analysis. The WLAN6102 is well positioned to take advantage of this growth," said Moses Asom, co-founder and senior vice president of marketing and business development, SyChip. "Mobile phone manufacturers are under constant pressure to reduce size, cut cost, and improve time to market and the WLAN6102 was designed from the start to address all these concerns."

SyChip's WLAN6102 sets the standard for 802.11g embedded module thickness and volume. It is simply the world's thinnest radio module at 0.9 mm. The WLAN6102 has a high level of integration with more than a dozen components designed into the substrate including critical components such as RF matching, band pass filter and balun. These components along with an on module EEPROM provides the customer with a true plug-and-play factory tested and calibrated module. At the same time the module architecture makes optimal use of existing phone system resources such as clock oscillators reducing the overall system cost. The feature set remains rich including WPA2 security, 802.11e QoS, enhanced power save features, advanced roaming capabilities, and proven coexistence for Cellular and Bluetooth protocols.

SyChip is demonstrating the WLAN6102 at CES 2006 in Las Vegas, January 5-8. You can visit SyChip at Booth # 9836 in the SD Card Association Pavilion at the Las Vegas Hilton Convention Center for a demonstration.

Pricing and Availability

The WLAN6102 is available for target account sampling and is packaged in a Ball Grid Array (BGA) form factor that allows for direct attachment to the main printed circuit board using industry standard surface mount technology. Pricing for the modules will be below \$14 per unit in volumes of 100,000.

For more information on WLAN6102, or other SyChip product, please visit <http://www.sychip.com/products.htm>.

About SyChip, Inc.

SyChip designs, develops and markets Radio Frequency Integrated Circuits and Chip Scale Modules for the wireless mobile market. The company focuses on developing RF modules that are differentiated due to proprietary integration, modular architectures, and low loss Silicon technologies. As a result of the proprietary integration, world-class RF system design, proprietary multifunction ASICs, software and smart utilities, SyChip's RF designs drastically reduce component count, offer very small footprints and are easy to integrate into a mobile device. Customers benefit by significantly reducing their time-to-market, increasing performance and improving reliability of their wireless devices. SyChip has received multiple awards, including the 2005 Deloitte Technology Fast 500 – number one in Texas and number ten in North America, the TiEcon 2005 Emerging Star Award, MobileTrax "2005 Mobility Award", finalist for the "2005 Red Herring 100", Deloitte's 2004 "Fast 500 Rising Star Award", "Best Wireless Accessory" by Handheld Computing, "Start-Up to Watch" by the Fabless Semiconductor Association (FSA), as well as being selected as Investors' Choice award winner at VentureWire's annual MicroVentures conference.

For more information about SyChip, please visit <http://www.sychip.com>.